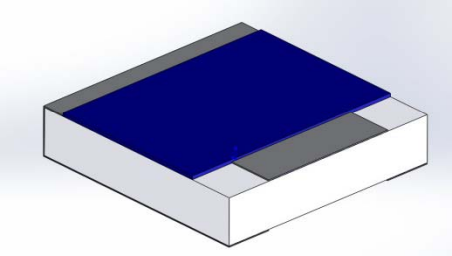
Model ANC200-200AG

Termination, Chip

Frequency Range: DC to 4.0 GHz, Power: 80 Watts



Features

- High Power
- Thin Film Resistor
- Terminal Ground Pad
- Surface Mount Configuration

This high power device is designed to dissipate power in RF circuits when mounted to an appropriate heat sink. The terminations provide a low VSWR under maximum power conditions.

Technical Specifications

Parameter	Value
Frequency Range	DC to 4.0 GHz
Impedance	50 ±5% Standard
Power Handling*	80 Watts Avg. Derated Linearly to 0 Watts @ +150°C
VSWR	DC – 2 GHz _____ 1.15:1 Max. 2 – 3 GHz _____ 1.30:1 Max. 3 – 4 GHz _____ 1.50:1 Max.
Temperature Range	-55°C to +150°C

Material

Feature	Material
Substrate	Aluminum Nitride
Resistor Material	Proprietary Thin Film
Terminal Finish	Silver – *(See "How to Order" for tinning & other options)*

*Mounting surfaces shall not exceed 100°C. Max.

How to Order

ANCT200-200AG-XXXX Y

Terminal Options
☐ = Silver over Nickel
T = Tin Lead Solder
H = Lead Free Solder

Ohm Value
50R0 = 50 Ohms
1000 = 100 Ohms

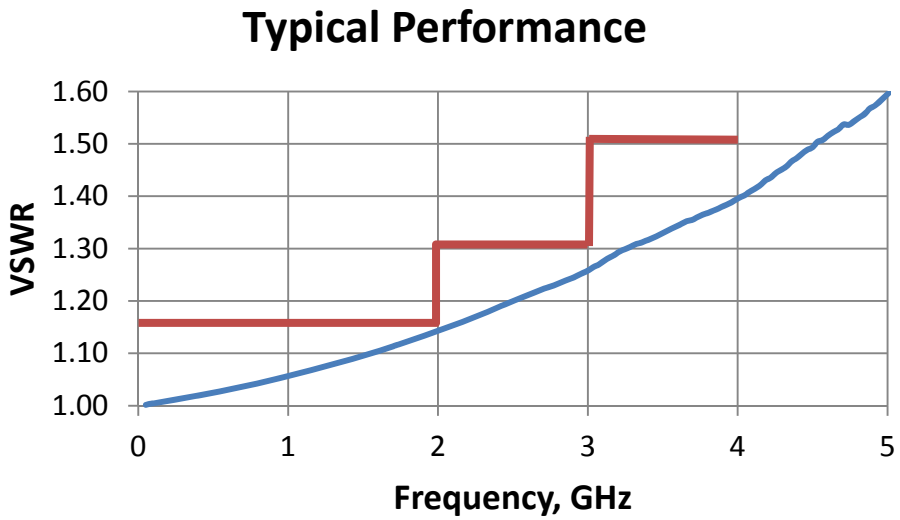
Tolerance
G = ±2%
J = ±5%

Ordering Examples

Model Number: ANC200-200AG-50R0J
DC – 4.0 GHz; 80 W.; 50 Ohms; 5%

Model Number: ANC200-200G-1000G
DC – 4.0 GHz; 80 W.; 100 Ohms; 2%

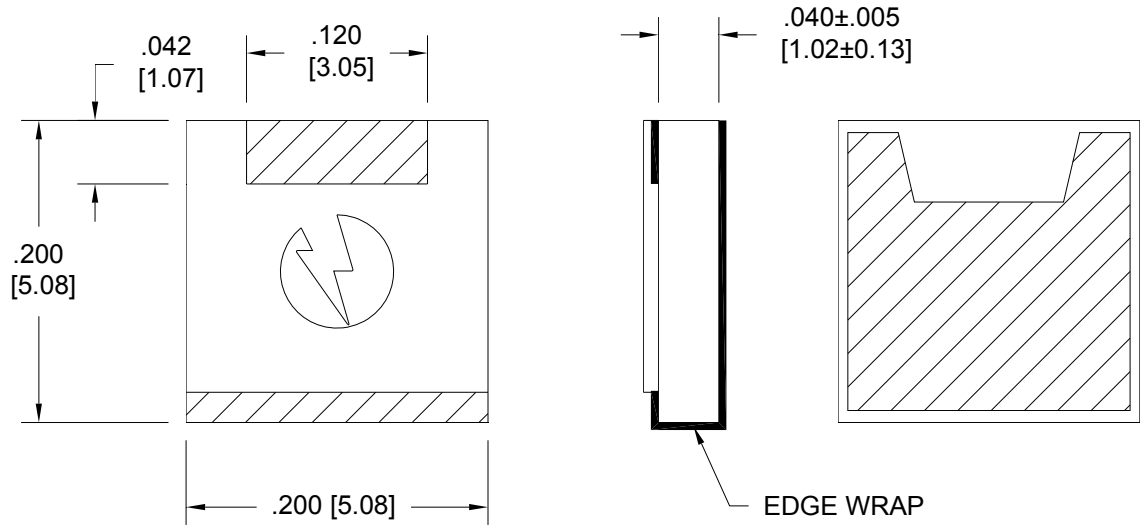
Performance Characteristics



Physical Dimensions

Model Number: ANC200-200AG-50R0J Shown

Tolerance: .XXX = ±.010



Dimensions are for substrate only and do not include terminal thickness or optional tinning thickness.